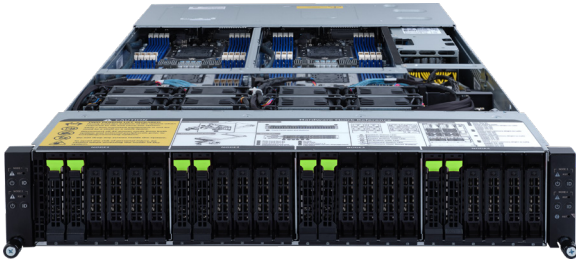


# H262-Z6B

## High Density Server - DP 2U 4 Nodes Gen4 NVMe



### Features

- Hardware-level root of trust support
- 2U - 4 nodes rear access server system
- Dual AMD EPYC™ 7003 Series processors
- 8-Channel RDIMM/LRDIMM DDR4 per processor, 64 x DIMMs
- 8 x 1Gb/s LAN ports (Intel® I350-AM2)
- 4 x Dedicated management ports
- 1 x CMC global management port
- 8 x 2.5" Gen4 U.2 hot-swappable SSD bays
- 4 x M.2 with PCIe Gen4 x4 interface
- 8 x Low profile PCIe Gen4 x16 expansion slots
- 4 x OCP 3.0 Gen4 x16 mezzanine slots
- 2200W (240V) 80 PLUS Platinum redundant PSU

### Specification

<b>Dimensions (WxHxD)</b>	2U 4 Nodes - Rear access 440 x 87.5 x 840 mm	<b>Rear I/O</b>	Per node: 2 x USB 3.0, 1 x Mini-DP, 2 x RJ45, 1 x MLAN Total: 8 x USB 3.0, 4 x Mini-DP, 8 x RJ45, 4 x MLAN, 1 x CMC
<b>Motherboard</b>	MZ62-HD4 Rev. 3.0	<b>Backplane I/O</b>	8 x ports Speed and bandwidth: SATA 6Gb/s or SAS 12Gb/s or PCIe Gen4 x4
<b>CPU</b>	AMD EPYC™ 7003 Series processors Dual processors, 7nm technology TDP up to 225W, cTDP up to 240W; Conditional support 280W Compatible with AMD EPYC™ 7002 Series processors 8 x LGA 4094 Socket SP3	<b>TPM</b>	1 x TPM header with SPI interface Optional TPM2.0 kit: CTM010
<b>Chipset</b>	System on Chip	<b>Power Supply</b>	Dual 2200W (240V) 80 PLUS Platinum redundant power supply
<b>Memory</b>	Total 64 x DIMM slots (16 x DIMM slots per node) DDR4 memory supported only 8-Channel memory architecture RDIMM/LRDIMM modules up to 128GB supported 3DS RDIMM/LRDIMM modules up to 256GB supported Memory speed: Up to 3200 MHz	<b>System Management</b>	Aspeed® AST2500 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
<b>LAN</b>	8 x 1GbE LAN ports (1 x Intel® I350-AM2) 4 x Dedicated management ports 1 x 10/100/1000 CMC global management port	<b>OS Compatibility</b>	Windows Server 2016 / 2019 RHEL 8.3 (x64) or later SLES 12 SP5 (x64) / 15 SP2 (x64) or later Ubuntu 18.04.5 LTS (x64) / 20.04 LTS (x64) or later VMware ESXi 6.7 Update3 P03 / 7.0 Update1 or later Citrix Hypervisor 8.2.0 or later
<b>Video</b>	Integrated in Aspeed® AST2500 2D Video Graphic Adapter with PCIe bus interface 1920x1200@60Hz 32bpp, DDR4 SDRAM	<b>Weight</b>	Net Weight: 28 kg / Gross Weight: 50 kg
<b>Storage</b>	8 x 2.5" Gen4 U.2 hot-swappable SSD bays All storage bays are compatible with SATA devices 4 x M.2 slot: - M-key, PCIe Gen4 x4 - Supports NGFF-2280/22110 cards	<b>System Fans</b>	8 x 80x80x38mm (16,300rpm)
<b>Expansion Slots</b>	8 x Low profile half-length slots with PCIe x16 (Gen4 x16) 4 x OCP 3.0 mezzanine slot (Gen4 x16)	<b>Operating Properties</b>	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
<b>Internal I/O</b>	Per node: 1 x M.2 slot, 1 x COM header, 1 x TPM header, 1 x BMC SGPIO header, 1 x JTAG BMC header, 1 x PLD header, 1 x Clear CMOS jumper, 1 x IPMB connector	<b>Packaging Content</b>	1 x H262-Z6B, 8 x CPU heatsinks, 1 x Rail kit
<b>Front I/O</b>	-	<b>Reference Numbers</b>	Barebone package: 6NH262Z6BMR-00 Rev. A00 Spare parts: - Motherboard: 9MZ62HD4NR-00 Rev. 3.0 - Rail kit: 25HB2-AN6103-K0R - CPU heatsink: 25ST1-44320H-A0R/25ST1-44320I-A0R - Back plane board: 9CBPH080NR-00 - Power Supply: 25EPO-222003-D0S - C19 type power cord 125V/15A (US): 25CP1-018000-Q0R (optional extra) - C19 type power cord 250V/16A (EU): 25CP3-01830H-Q0R (optional extra) - C19 type power cord 250V/15A (US): 25CP1-018300-Q0R (optional extra) - Ring topology kit: 6NH262Z65SR-00-100 (optional extra)

\* All specifications are subject to change without notice. Please visit our website for the latest information.

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